

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6524611

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
SEQUENCE:	3

CONVEYING PARTY DATA

Name	Execution Date
SUNEDISON SEMICONDUCTOR LIMITED (UEN201334164H)	06/06/2018

RECEIVING PARTY DATA

Name:	GLOBALWAFERS CO., LTD.
Street Address:	NO. 8 INDUSTRIAL EAST ROAD 2
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSINCHU
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17162729

CORRESPONDENCE DATA**Fax Number:** (314)612-2307***Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.*****Phone:** 314-621-5070**Email:** USpatents@armstrongteasdale.com, clager@armstrongteasdale.com**Correspondent Name:** PATENT DOCKET DEPARTMENT ARMSTRONG TEASD**Address Line 1:** 7700 FORSYTH BOULEVARD**Address Line 2:** SUITE 1800**Address Line 4:** ST. LOUIS, MISSOURI 63105

ATTORNEY DOCKET NUMBER:	28744-5327 (120060.4)
NAME OF SUBMITTER:	MICHAEL G. MUNSELL
SIGNATURE:	/Michael G. Munsell/
DATE SIGNED:	01/29/2021

Total Attachments: 7

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ASSIGNMENT

This Assignment is made by and among SunEdison Semiconductor Limited, a company organized and existing under the laws of Singapore (“SSL”), MEMC Japan Limited, a company organized and existing under the laws of Japan (“MEMC Japan”), and MEMC Electronic Materials, S.P.A., a company organized and existing under the laws of Italy (“MEMC EM”, and collectively with SSL and MEMC Japan, the “Assignors”), and GlobalWafers Co., Ltd., a company organized and existing under the laws of Taiwan and having its registered address at No. 8, Industrial East Road, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C. (hereinafter referred to as “Assignee”);

WHEREAS, on December 31, 2016, Assignors entered into certain IP Transfer Agreements with Assignee;

WHEREAS, the parties hereto desire to memorialize, *nunc pro tunc*, the assignment and ownership of all Assigned IP (defined below) for, among other things, recordal purposes with certain patent administration bodies, such as the United States Patent and Trademark Office; and

WHEREAS, Assignors acknowledge that payment in full from Assignee for all Assigned IP has heretofore been paid.

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, Assignors have agreed to and do hereby sell, assign and transfer, and confirm the sale, assignment and transfer, unto Assignee all of their rights, title and interest throughout the world, including without limitation, the right to sue and recover for any past infringements, in and to the Listed IP, any other applications (including provisional, non-provisional, divisional, continuing, or reissue applications) based in whole or in part on any Listed IP, any corresponding patent or patent applications filed in any country based in whole or in part on, and/or claiming priority from, any Listed IP, any patents (including extensions thereof) of any country based in whole or in part on, and/or claiming priority from, any Listed IP, and all of the inventions described in the Listed IP and all of the aforementioned patents and patent applications (all of the foregoing, collectively, the “Assigned IP”);

TO BE HELD AND ENJOYED by said Assignee, its successors and assigns, as fully and entirely as the Assigned IP would have been held and enjoyed by Assignors had no assignment of said interest been made.

EACH ASSIGNOR hereby agrees that it will do, execute and deliver, or will cause to be done, executed and delivered, all such further lawful acts, transfers, assignments and conveyances, powers of attorney and assurances for the better assuring, conveying and confirming unto Assignee, all of such Assignor's rights, title and interest in and to the Assigned IP hereby transferred, assigned and conveyed, as Assignee may reasonably require.

[Signature Pages Follow]

IN WITNESS WHEREOF, the undersigned have caused these presents to be executed by their respective officers thereunto duly authorized this 6 day of June, 2018.

Assignor:

SUNEDISON SEMICONDUCTOR LIMITED

By: *Paul Markowitz*

Name: Paul Markowitz

Title: Director of Intellectual Property

STATE OF Missouri
COUNTY OF St. Charles

On this 6 day of June, 2018, before me, a Notary Public, personally appeared Paul Markowitz, an officer of SUNEDISON SEMICONDUCTOR LIMITED, known to me to be the person who executed the within Assignment, and who did state that said instrument was signed on behalf of said company, and acknowledged to me that he executed the same for the purposes therein stated.

IN TESTIMONY WHEREOF, I have hereunto set my hand and seal the date and year last above written.

Erika Damiani
Notary Public


My Commission Expires:

July 20, 2018



Assignor:

MEMC JAPAN LTD

By: 


Name: Paul Markowitz

Title: Director of Intellectual Property

STATE OF Missouri
COUNTY OF St. Charles

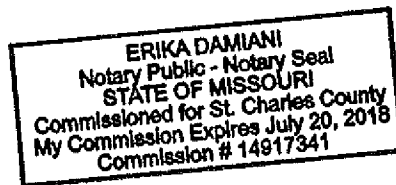
On this 6 day of June, 2018, before me, a Notary Public, personally appeared Paul Markowitz, an officer of MEMC JAPAN LTD, known to me to be the person who executed the within Assignment, and who did state that said instrument was signed on behalf of said company, and acknowledged to me that he executed the same for the purposes therein stated.

IN TESTIMONY WHEREOF, I have hereunto set my hand and seal the date and year last above written.


Notary Public

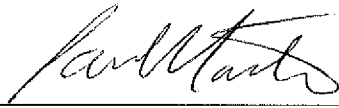
My Commission Expires:

July 20, 2018



Assignor:

MEMC ELECTRONIC MATERIALS S.P.A.

By: 


Name: Paul Markowitz

Title: Director of Intellectual Property

STATE OF Missouri)
COUNTY OF St. Charles)

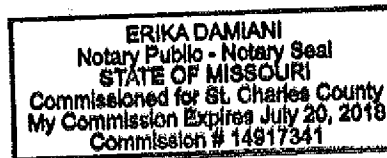
On this 6 day of June, 2018, before me, a Notary Public, personally appeared Paul Markowitz, an officer of MEMC ELECTRONIC MATERIALS S.P.A., known to me to be the person who executed the within Assignment, and who did state that said instrument was signed on behalf of said company, and acknowledged to me that he executed the same for the purposes therein stated.

IN TESTIMONY WHEREOF, I have hereunto set my hand and seal the date and year last above written.


Notary Public

My Commission Expires:

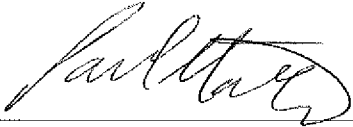
July 20, 2018



For and on behalf of GlobalWafers Co., Ltd.

Assignee:

GLOBALWAFERS CO., LTD.

By: 

Name: Paul Markowitz

Title: Director of Intellectual Property

STATE OF Missouri)
COUNTY OF St. Charles

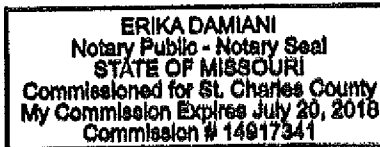
On this 6 day of June, 2018, before me, a Notary Public, personally appeared Paul Markowitz, an officer of GLOBALWAFERS CO., LTD., known to me to be the person who executed the within Assignment, and who did state that said instrument was signed on behalf of said company, and acknowledged to me that he executed the same for the purposes therein stated.

IN TESTIMONY WHEREOF, I have hereunto set my hand and seal the date and year last above written.


Notary Public

My Commission Expires:

July 20, 2018



SCHEDULE A

TITLE	Country	Application Number	Filing Date	Publication Number	Publication Date	Patent Number	Issue Date
SYSTEMS AND METHODS FOR REDUCING DUST IN GRANULAR MATERIAL	DE	112014001339.0	11-Sep-2015	DE112014001339 T5	26-Nov-2015		
LINER ASSEMBLIES FOR SUBSTRATE PROCESSING SYSTEMS	US	14/176263	10-Feb-2014	2014-0224174	14-Aug-2014		
PROCESS FOR PREPARING LOW DEFECT DENSITY SILICON USING HIGH GROWTH RATES	JP	2010-155726	8-Jul-2010	2010-265172	25-Nov-2010	5517799	11-Apr-2014
PROCESS FOR PREPARING LOW DEFECT DENSITY SILICON USING HIGH GROWTH RATES	US	09/871255	31-May-2001	2002-0053315	9-May-2002	6689209	10-Feb-2004
GAS DISTRIBUTION PLATE FOR CHEMICAL VAPOR DEPOSITION SYSTEMS AND METHODS OF USING SAME	US	13/828926	14-Mar-2013	2014-0273409	18-Sep-2014	9328420	3-May-2016
INJECT INSERT LINER ASSEMBLIES FOR CHEMICAL VAPOR DEPOSITION SYSTEMS AND METHODS OF USING SAME	US	13/829021	14-Mar-2013	2014-0273410	18-Sep-2014	9117670	25-Aug-2015
DOPANT FEEDING DEVICE FOR DISPENSING DOPANT SYSTEMS AND METHODS FOR INTERFEROMETRIC PHASE MEASUREMENT	US	14/906462	20-Jan-2016	2016-0298259	13-Oct-2016		
METHOD AND SYSTEM FOR ARRANGING NUMERIC DATA FOR COMPRESSION	US	14/095624	3-Dec-2013	2015-0153166	4-Jun-2015	9384540	5-Jul-2016
GAS DOPING SYSTEMS FOR CONTROLLED DOPING OF A MELT OF SEMICONDUCTOR OR SOLAR-GRADE MATERIAL	US	14/774310	10-Sep-2015	2016-0017513	21-Jan-2016		
GAS DOPING SYSTEMS FOR CONTROLLED DOPING OF A MELT OF SEMICONDUCTOR OR SOLAR-GRADE MATERIAL	JP	2015-562564	14-Sep-2015	2016-509989	4-Apr-2016	6317374	6-Apr-2018
GAS DOPING SYSTEMS FOR CONTROLLED DOPING OF A MELT OF SEMICONDUCTOR OR SOLAR-GRADE MATERIAL	JP	2017-210841	31-Oct-2017	2018-016543	1-Feb-2018		
SINGLE SIDE POLISHING USING SHAPE MATCHING	US	13/801105	13-Mar-2013	2014-0273748	18-Sep-2014	9193025	24-Nov-2015
CENTER FLEX SINGLE SIDE POLISHING HEAD	US	14/292837	31-May-2014	2014-0357161	4-Dec-2014		
METHODS FOR PRODUCING LOW OXYGEN SILICON INGOTS	US	14/893280	23-Nov-2015	2016-0108551	21-Apr-2016	9951440	24-Apr-2018
METHODS FOR PRODUCING LOW OXYGEN SILICON INGOTS	US	15/959964	23-Apr-2018				

PATENT

REEL: 055083 FRAME: 0852

RECORDED: 01/29/2021